

<b>PCN Number:</b>	20130401002		<b>PCN Date:</b>	04/08/2013										
<b>Title:</b>	Qualification of TI Clark as Additional Assembly/Test Site for DRV8833RTY device													
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services									
<b>Proposed 1<sup>st</sup> Ship Date:</b>	07/08/2013		<b>Estimated Sample Availability:</b>	Date Provided at Sample request										
<b>Change Type:</b>														
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials									
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification									
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process									
<b>PCN Details</b>														
<b>Description of Change:</b>														
Qualification of TI Clark as additional assembly and test site for DRV8833RTY device. The device in the product affected list is being qualified by similarity (see Qualification Data).														
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.														
<b>Reason for Change:</b>														
Continuity of Supply														
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>														
None														
<b>Changes to product identification resulting from this PCN:</b>														
<table border="1"> <tr> <td colspan="3">Assembly Site</td> </tr> <tr> <td>TI Malaysia</td> <td>Assembly Site Origin (22L)</td> <td>ASO: MLA</td> </tr> <tr> <td>TI Clark Philippines</td> <td>Assembly Site Origin (22L)</td> <td>ASO: QAB</td> </tr> </table>						Assembly Site			TI Malaysia	Assembly Site Origin (22L)	ASO: MLA	TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB
Assembly Site														
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA												
TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB												
Sample product shipping label (not actual product label)														
<b>Device Marking</b>														
<table border="1"> <tr> <td>O</td> </tr> <tr> <td>{CUST1}</td> </tr> <tr> <td>TI YMS</td> </tr> <tr> <td>LLLL</td> </tr> </table>			O	{CUST1}	TI YMS	LLLL	TI = TI LETTERS YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = PIN 1 INDICATOR							
O														
{CUST1}														
TI YMS														
LLLL														
<b>Topside Device marking:</b>														
Assembly site code for MLA = K														
Assembly site code for TI-Clark = I														

**Product Affected:**

DRV8833RTYR

DRV8833RTYT

**Reference Qualification: QFN Package at TI-Clark****Qualification Data: Approved 08/24/2010**

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

**Qual Vehicle : TPA2017D2RTJ (MSL 2-260C)****Package Construction Details**

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	20-RTJ, QFN	Mount Compound:	4207768
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	0.96 Mil Dia., Cu
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
**High Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temp Cycle, -65C/150C	500 Cycles	77/0	77/0	77/0
**Thermal Shock, -65C/150C	500 Cycles	77/0	77/0	77/0
Bond Pull	76 ball bonds, min. 3 units	76/0	76/0	76/0
Bond Shear	76 ball bonds, min. 3 units	76/0	76/0	76/0
Salt Atmosphere	-	22/0	22/0	22/0
Surface Mount Solderability	Pb Free Solder	22/0	22/0	22/0
Manufacturability Qualification (MQ)	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	Level 2-260C	12/0	12/0	12/0
X-ray	(top side only)	5/0	5/0	5/0

\*\* - Preconditioning sequence: Level 2-260C.

Qual Vehicle 2 : TPS61202DSC (MSL 2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	10-DSC, QFN	Mount Compound:	4207768	
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	2.0 Mil Dia., Cu	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
**High Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temp Cycle, -65C/150C	500 Cycles	77/0	77/0	77/0
**Thermal Shock, -65C/150C	500 Cycles	77/0	77/0	77/0
Bond Pull	76 ball bonds, min. 3 units	76/0	76/0	76/0
Bond Shear	76 ball bonds, min. 3 units	76/0	76/0	76/0
Salt Atmosphere	-	22/0	22/0	22/0
Surface Mount Solderability	Pb Free Solder	22/0	22/0	22/0
Manufacturability Qualification (MQ)	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	Level 2-260C	12/0	12/0	12/0
X-ray	(top side only)	5/0	5/0	5/0
**- Preconditioning sequence: Level 2-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>